RF COMMUNICATIONS PRODUCTS



Product specification

April 15, 1992

Philips Semiconductors



IC11



NE/SE5539

DESCRIPTION

The NE/SE5539 is a very wide bandwidth, high slew rate, monolithic operational amplifier for use in video amplifiers, RF amplifiers, and extremely high slew rate amplifiers.

Emitter-follower inputs provide a true differential input impedance device. Proper external compensation will allow design operation over a wide range of closed-loop gains, both inverting and non-inverting, to meet specific design requirements.

FEATURES

- Bandwidth
 - Unity gain 350MHz
 - Full power 48MHz
- GBW 1.2GHz at 17dB
- Slew rate: 600/Vµs
- A_{VOL}: 52dB typical
- Low noise 4nV√Hz typical
- MIL-STD processing available

APPLICATIONS

- High speed datacom
- Video monitors & TV

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
14-Pin Plastic Dual In-Line Package (DIP)	0 to +70°C	NE5539N	SOT27-1
14-Pin Plastic Small Outline (SO) package	0 to +70°C	NE5539D	SOT108-1
14-Pin Ceramic Dual In-Line Package	0 to +70°C	NE5539F	0581B
14-Pin Ceramic Dual In-Line Package	-55 to +125°C	SE5539F	0581B

PIN CONFIGURATION

+ INPUT

-VSUPPLY

VOSADJ

AV APJ 6

GROUND

• Satellite communications

Military communications

• RF instrumentation & oscillators

Image processing

Magnetic storage

NC 2

NC 4

1

3

5

7

D, F, N Packages

Top View

Figure 1. Pin Configuration

14

13 NC

12 11 NC

10 +V

9 NC

8 OUTPUT

- INPUT

FREQUENCY COMPENS.

SL00570

ABSOLUTE MAXIMUM RATINGS¹

SYMBOL	PARAMETER	RATING	UNITS
V _{CC}	Supply voltage	±12	V
P _{DMAX}	Maximum power dissipation, $T_A = 25^{\circ}C \text{ (still-air)}^2$ F package N package D package	1.17 1.45 0.99	W W W
T _A	Operating temperature range NE SE	0 to 70 -55 to +125	°C O°
T _{STG}	Storage temperature range	-65 to +150	°C
TJ	Max junction temperature	150	°C
T _{SOLD}	Lead soldering temperature (10sec max)	+300	°C

NOTES:

Differential input voltage should not exceed 0.25V to prevent excesive input bias current and common-mode voltage 2.5V. These voltage 1. limits may be exceeded if current is limited to less than 10mA.

2. Derate above 25°C, at the following rates:

- F package at 9.3mW/°C
- N package at 11.6mW/°C D package at 7.9mW/°C

NE/SE5539

EQUIVALENT CIRCUIT



Figure 2. Equivalent Circuit

DC ELECTRICAL CHARACTERISTICS

 V_{CC} = ±8V, T_A = 25 $^{\circ}C;$ unless otherwise specified.

SYMBOL	DADAMETED	TEST CONDI	IONE		SE5539			NE5539		UNITE
STWBUL	PARAMETER	TEST CONDIT	TEST CONDITIONS		TYP	MAX	MIN	TYP	MAX	
V	land the standard sector		Over temp		2	5				
VOS	Input onset voltage	$V_0 = 0V, R_S = 100\Omega$	$T_A = 25^{\circ}C$		2	3		2.5	5	mv
	$\Delta V_{OS} / \Delta T$				5			5		μV/°C
	logist offerst summert		Over temp		0.1	3				
I _{OS} Input offset current		$T_A = 25^{\circ}C$		0.1	1			2	μΑ	
	$\Delta I_{OS} / \Delta T$				0.5			0.5		nA/°C
	lanut king gumant		Over temp		6	25				
IВ	Input bias current		$T_A = 25^{\circ}C$		5	13		5	20	μΑ
	$\Delta I_{B} / \Delta T$				10			10		nA/°C
CMDD	Common mode rejection ratio	F = 1kHz, R _S = 100Ω	2, V _{CM} ±1.7V	70	80		70	80		٩D
CIVIRR	Common mode rejection ratio		Over temp	70	80					uв
R _{IN}	Input impedance				100			100		kΩ
R _{OUT}	Output impedance				10			10		Ω

DC ELECTRICAL CHARACTERISTICS (Continued)

 V_{CC} = $\pm 8 V,\, T_A$ = $25^\circ C;$ unless otherwise specified.

CVMPOI	DADAMETED	TEST CONDITIC			SE5539		NE5539			LINITS
STMBOL	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	
V _{OUT}	Output voltage swing	$R_L = 150\Omega$ to GND and 470Ω to -V _{CC}	+Swing -Swing				+2.3 -1.7	+2.7 -2.2		V
Varia		$R_L = 25\Omega$ to GND Over temp	+Swing -Swing	+2.3 -1.5	+3.0 -2.1					V
VOUT	Output voltage swillig	$R_L = 25\Omega$ to GND $T_A = 25^{\circ}C$	+Swing -Swing	+2.5 -2.0	+3.1 -2.7					v
		$V_0 = 0, R_1 = \infty, Ove$	er temp		14	18				m A
'CC+	Positive supply current	$V_{O} = 0, R_{1} = \infty, T_{A} = 25^{\circ}C$			14	17		14	18	ША
	Negative europhy europat	$V_0 = 0, R_1 = \infty$, Over temp			11	15				
ICC-	Negative supply current	$V_{O} = 0, R_{1} = \infty, T_{A} = 25^{\circ}C$			11	14		11	15	mA
	$\Delta V_{CC} = \pm 1 V$, Over temp			300	1000					
FORK	Power supply rejection ratio	$\Delta V_{CC} = \pm 1 V$, $T_A = 25^{\circ}C$						200	1000	μν/ν
A _{VOL}	Large signal voltage gain	V _O = +2.3V, -1.7V, R _L = GND, 470Ω to -\	= 150Ω to / _{CC}				47	52	57	dB
A _{VOL}	Large signal voltage gain	V _O = +2.3V, -1.7V	Over temp							dB
		$R_L = 2\Omega$ to GND	T _A = 25°C				47	52	57	
A _{VOL}	Large signal voltage gain	V _O = +2.5V, -2.0V	Over temp	46		60				dB
		$R_L = 2\Omega$ to GND	T _A = 25°C	48	53	58				

DC ELECTRICAL CHARACTERISTICS

 V_{CC} = $\pm 6V,\,T_{A}$ = $25^{\circ}C;$ unless otherwise specified.

SYMPOL	DADAMETER	TEST CONDITIONS				SE5539		UNITO
STMBOL	PARAMETER					TYP	MAX	UNITS
V	Innut offect veltoge			Over temp		2	5	
VOS	input onset voltage			T _A = 25°C		2	3	mv
	Input offect ourrent			Over temp		0.1	3	
'OS	input onset current			$T_A = 25^{\circ}C$		0.1	1	μΑ
	Innut higg ourrest			Over temp		5	20	A
IВ	Input bias current			T _A = 25°C		4	10	μΑ
CMRR	Common-mode rejection ratio	$V_{CM} = \pm 1.3 V, R_{S} = 100 \Omega$			70	85		dB
				Over temp		11	14	
ICC+	Positive supply current			T _A = 25°C		11	13	ША
				Over temp		8	11	~ ^
'CC-	Negative supply current		$T_A = 25^{\circ}CmA$		8	10	ША	
	Dower eventy rejection ratio			Over temp		300	1000	
PSKK	Power supply rejection ratio	$\Delta v_{CC} = \pm 1 v$		T _A = 25°C				μν/ν
			Over	+Swing	+1.4	+2.0		
V _{OUT}		$R_L = 150\Omega$ to GND	temp	-Swing	-1.1	-1.7		V
	Output voltage swing	and 390 Ω to –V _{CC}	T _A =	+Swing	+1.5	+2.0		v
			25°C	-Swing	-1.4	-1.8		

NE/SE5539

AC ELECTRICAL CHARACTERISTICS

 V_{CC} = $\pm 8V,\,R_L$ = 150 Ω to GND and 470 Ω to -V_{CC}, unless otherwise specified.

SYMPOL	DADAMETED	TEST CONDITIONS		SE5539			NE5539		UNITO
STMBOL	PARAMETER			TYP	MAX	MIN	TYP	MAX	UNITS
BW	Gain bandwidth product	$A_{CL} = 7, V_{O} = 0.1 V_{P-P}$		1200			1200		MHz
	Small signal bandwidth	$A_{CL} = 2, R_{L} = 150\Omega^{1}$		110			110		MHz
t _S	Settling time	$A_{CL} = 2, R_{L} = 150\Omega^{1}$		15			15		ns
SR	Slew rate	$A_{CL} = 2, R_{L} = 150\Omega^{1}$		600			600		V/μs
t _{PD}	Propagation delay	$A_{CL} = 2, R_{L} = 150\Omega^{1}$		7			7		ns
	Full power response	$A_{CL} = 2, R_{L} = 150\Omega^{1}$		48			48		MHz
	Full power response	$A_V = 7, R_L = 150\Omega^1$		20			20		MHz
	Input noise voltage	R _S = 50Ω, 1MHz		4			4		nV/√Hz
	Input noise current	1MHz		6			6		pA/√Hz

NOTES:

1. External compensation.

AC ELECTRICAL CHARACTERISTICS

 V_{CC} = $\pm 6V,\,R_L$ = 150 Ω to GND and 390 Ω to -V_{CC}, unless otherwise specified.

SAMBOL	DADAMETED	PARAMETER TEST CONDITIONS		SE5539				
STMBOL	FARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS		
D\A/	Gain bandwidth product	A _{CL} = 7		700				
Small signal bandwidth A _C		$A_{CL} = 2^1$		120				
t _S	Settling time	$A_{CL} = 2^1$		23		ns		
SR	Slew rate	$A_{CL} = 2^1$		330		V/μs		
t _{PD}	Propagation delay	$A_{CL} = 2^1$		4.5		ns		
	Full power response	$A_{CL} = 2^1$		20		MHz		

NOTES:

1. External compensation.

TYPICAL PERFORMANCE CURVES



Figure 3. NE5539 Open-Loop Phase



Figure 4. NE5539 Open-Loop Gain

TYPICAL PERFORMANCE CURVES (Continued)



Figure 5. Typical Performance Curves

CIRCUIT LAYOUT CONSIDERATIONS

As may be expected for an ultra-high frequency, wide-gain bandwidth amplifier, the physical circuit is extremely critical.

Bread-boarding is not recommended. A double-sided copper-clad printed circuit board will result in more favorable system operation. An example utilizing a 28dB non-inverting amp is shown in Figure 6.



Figure 6. 28dB Non-Inverting Amp Sample PC Layout

NE/SE5539

NE5539 COLOR VIDEO AMPLIFIER

The NE5539 wideband operational amplifier is easily adapted for use as a color video amplifier. A typical circuit is shown in Figure 7 along with vector-scope1 photographs showing the amplifier differential gain and phase response to a standard five-step modulated staircase linearity signal (Figures 8, 9 and 10). As can be seen in Figure 9, the gain varies less than 0.5% from the bottom to the top of the staircase. The maximum differential phase shown in Figure 10 is approximately +0.1°.

The amplifier circuit was optimized for a 75Ω input and output termionation impedance with a gain of approximately 10 (20dB).

NOTE:

1. The input signal was 200mV and the output 2V. V_{CC} was $\pm 8V$.



Figure 7. NE5539 Video Amplifier



Figure 8. Input Signal



Figure 9. Differential Gain <0.5%

NOTE:

Instruments used for these measurements were Tektronix 146 NTSC test signal generator, 520A NTSC vectorscope, and 1480 waveform monitor.



Figure 10. Differential Gain +0.1°



Figure 11. Non-Inverting Follower



Figure 12. Inverting Follower

mm

inches

Note

4.2

0.17

0.51

0.020

3.2

0.13

High frequency operational amplifier





SOT27-1

NE/SE5539

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

1.13

0.068

0.044

0.38

0.021

0.015

0.23

0.014

0.009

18.55

0.77

0.73

6.20

0.26

0.24

OUTLINE	INE REFERENCES				EUROPEAN	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001AA				-92-11-17 95-03-11

2.54

0.10

7.62

0.30

3.05

0.14

0.12

7.80

0.32

0.31

8.3

0.39

0.33

0.254

0.01

2.2

0.087

NE/SE5539



1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES		EUROPEAN	
VERSION	IEC	JEDEC EIAJ PRO		PROJECTION	ISSUE DATE	
SOT108-1	076E06S	MS-012AB				91-08-13 95-01-23



0581B 14-PIN (300 mils wide) CERAMIC DUAL IN-LINE (F) PACKAGE

High frequency operational amplifier

NE/SE5539

DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.					
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